

**1/4- to 1/11-DUTY FIP™ (VFD) CONTROLLER/DRIVER**

The  $\mu$ PD16312 is a FIP (fluorescent Indicator Panel, or Vacuum Fluorescent Display) controller/driver that is driven on a 1/4- to 1/11 duty factor. It consists of 11 segment output lines, 6 grid output lines, 5 segment/grid output drive lines, a display memory, a control circuit, and a key scan circuit. Serial data is input to the  $\mu$ PD16312 through a three-line serial interface. This FIP controller/driver is ideal as a peripheral device for a single-chip microcomputer.

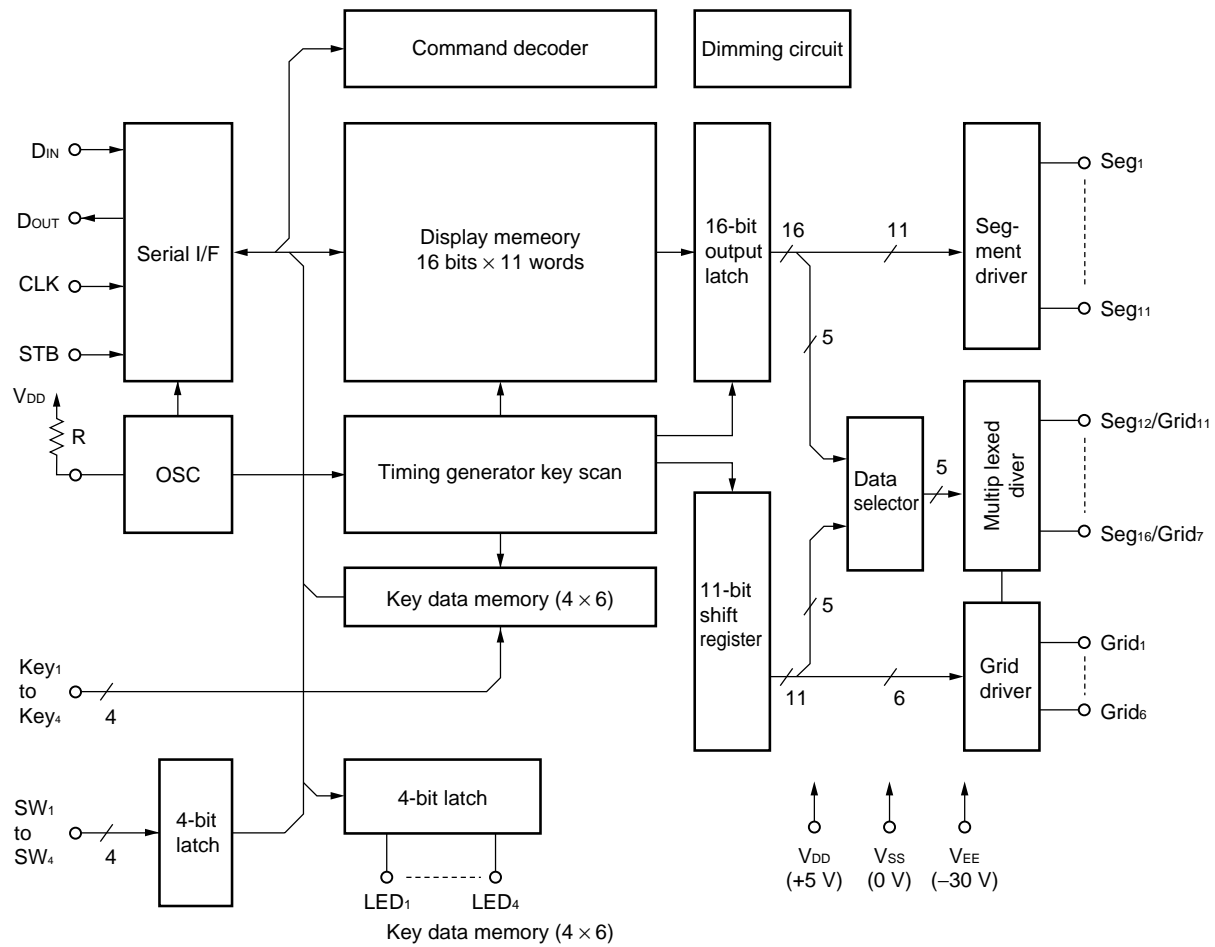
**FEATURES**

- Multiple display modes (11-segment & 11-digit to 16-segment & 4-digit)
- Key scanning (6 × 4 matrix)
- Dimming circuit (eight steps)
- High-voltage output ( $V_{DD} - 35\text{ V max}$ ).
- LED ports (4 chs., 20 mA max).
- General-purpose input port (4 bits)
- No external resistors necessary for driver outputs (P-ch open-drain + pull-down resistor output)
- Serial interface (CLK, STB, DIN, DOUT)

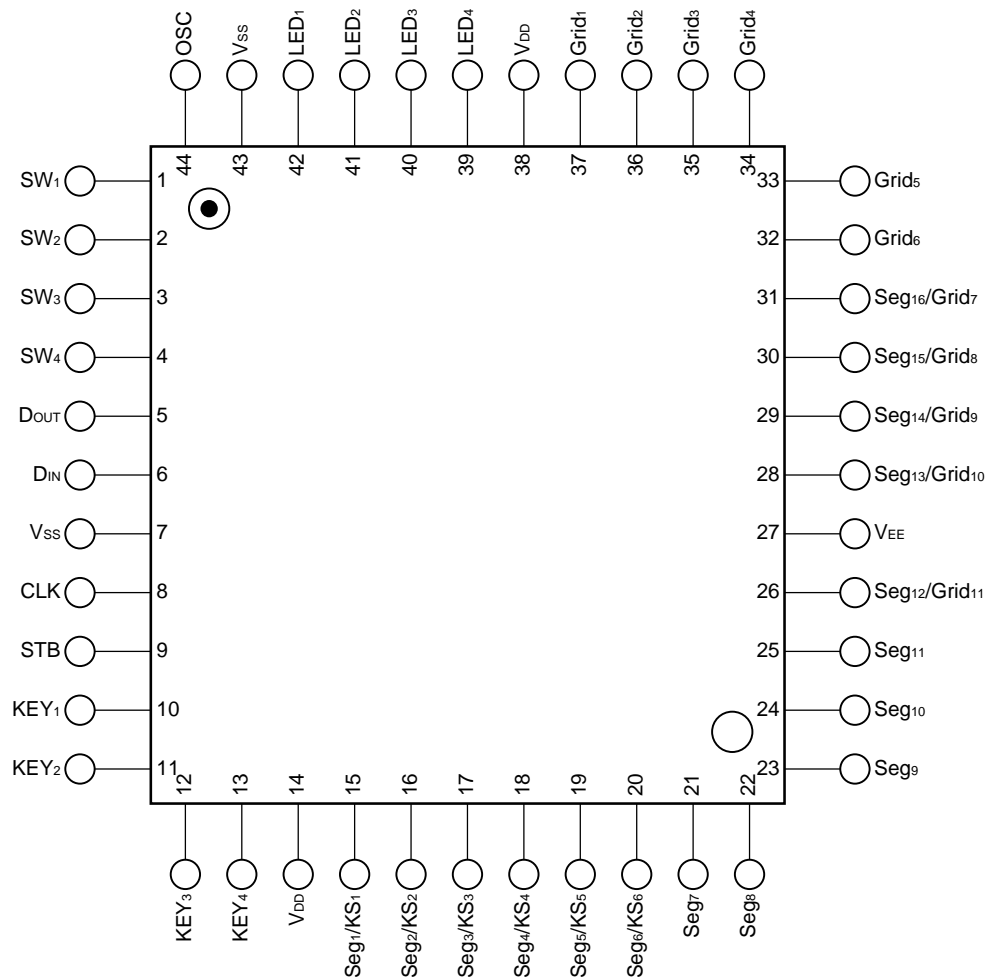
**ORDERING INFORMATION**

Part Number	Package
$\mu$ PD16312GB-3B4	44-pin plastic QFP ( $\square 10$ )

BLOCK DIAGRAM



PIN CONFIGURATION (Top View)



Use all power pins.

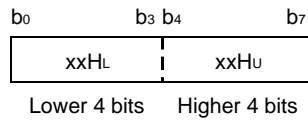
Pin Function

Symbol	Pin Name	Pin No	Description
D <sub>IN</sub>	Data input	6	Input serial data at rising edge of shift clock, starting from the low order bit.
D <sub>OUT</sub>	Data output	5	Output serial data at the falling edge of the shift clock, starting from low order bit. This is N-ch open-drain output pin.
STB	Strobe	9	Initializes serial interface at the rising or falling edge of the μPD16312. It then waits for reception of a command. Data input after STB has fallen is processed as a command. While command data is processed, current processing is stopped, and the serial interface is initialized. While STB is high, CLK is ignored.
CLK	Clock input	8	Reads serial data at the rising edge, and outputs data at the falling edge.
OSC	Oscillator pin	44	Connect resistor to this pin to determine the oscillation frequency to this pin.
Seg <sub>1</sub> /KS <sub>1</sub> to Seg <sub>6</sub> /KS <sub>6</sub>	High-voltage output	15 to 20	Segment output pins (Dual function as key source)
Seg <sub>7</sub> to Seg <sub>11</sub>	High-voltage output (segment)	21 to 25	Segment output pins
Grid <sub>1</sub> to Grid <sub>6</sub>	High-voltage output (grid)	37 to 32	Grid output pins
Seg <sub>12</sub> /Grid <sub>11</sub> to Seg <sub>16</sub> /Grid <sub>7</sub>	High-voltage output (segment/grid)	26, 28 to 31	These pins are selectable for segment or grid driving.
LED <sub>1</sub> to LED <sub>4</sub>	LED output	42 to 39	CMOS output. +20 mA max.
KEY <sub>1</sub> to KEY <sub>4</sub>	Key data input	10 to 13	Data input to these pins is latched at the end of the display cycle.
SW <sub>1</sub> to SW <sub>4</sub>	Switch input	1 to 4	These pins constitute a 4-bit general-purpose input port.
V <sub>DD</sub>	Logic power	14, 38	5 V ± 10 %
V <sub>SS</sub>	Logic ground	7, 43	Connect this pin to system GND.
V <sub>EE</sub>	Pull-down level	27	V <sub>DD</sub> – 35 V max.

**Display RAM Address and Display Mode**

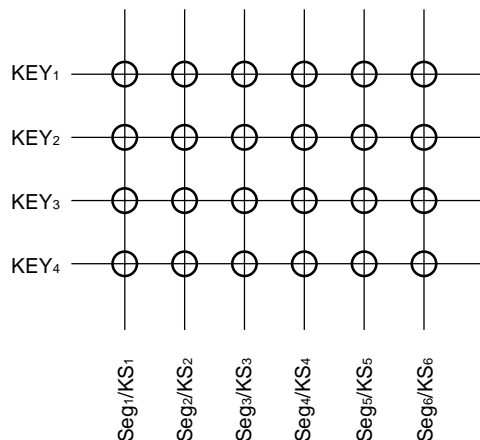
The display RAM stores the data transmitted from an external device to the μPD16312 through the serial interface, and is assigned addresses as follows, in 8 bits unit:

Seg <sub>1</sub>	Seg <sub>4</sub>	Seg <sub>8</sub>	Seg <sub>12</sub>	Seg <sub>16</sub>	
00HL	00Hu	01HL	01Hu		DIG <sub>1</sub>
02HL	02Hu	03HL	03Hu		DIG <sub>2</sub>
04HL	04Hu	05HL	05Hu		DIG <sub>3</sub>
06HL	06Hu	07HL	07Hu		DIG <sub>4</sub>
08HL	08Hu	09HL	09Hu		DIG <sub>5</sub>
0AHL	0AHu	0BHL	0BH <sub>u</sub>		DIG <sub>6</sub>
0CHL	0CH <sub>u</sub>	0DHL	0DH <sub>u</sub>		DIG <sub>7</sub>
0EHL	0EH <sub>u</sub>	0FHL	0FH <sub>u</sub>		DIG <sub>8</sub>
10HL	10Hu	11HL	11Hu		DIG <sub>9</sub>
12HL	12Hu	13HL	13Hu		DIG <sub>10</sub>
14HL	14Hu	15HL	15Hu		DIG <sub>11</sub>

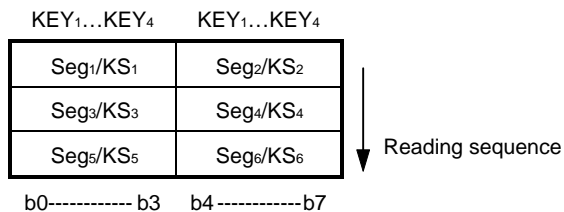


### Key Matrix and Key-Input Data Storage RAM

The key matrix is made up of a 6 × 4 matrix, as shown below.

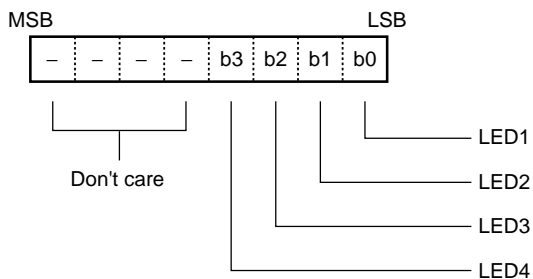


The data of each key is stored as illustrated below, and is read with the read command, starting from the least significant bit.



### LED Port

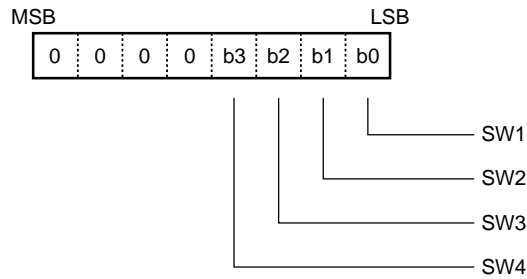
Data is written to the LED port with the write command, starting from the least port's least significant bit. When a bit of this port is 0, the corresponding LED lights; when the bit is 1, the LED turns off. The data of bits 5 through 8 are ignored.



On power application, all LEDs are unlit.

**SW Data**

SW data is read with the read command, starting from the least significant bit. Bits 5 through 8 of the SW data are 0.



**Commands**

Commands set the display mode and status of the FIP driver.

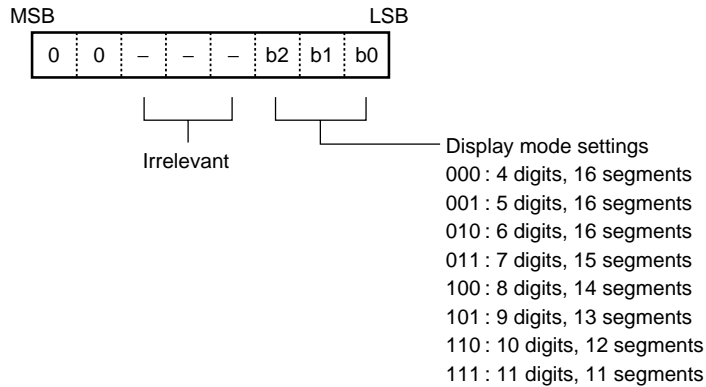
The first 1 byte input to the μPD16312 through the D<sub>IN</sub> pin after the STB pin has fallen is regarded as a command.

If STB is set high while commands/data are transmitted, serial communication is initialized, and the commands/data being transmitted are invalid (however, the commands/data previously transmitted remain valid).

**(1) Display mode setting commands**

These commands initialize the μPD16312 and select the number of segments and the number of grids (1/4 to 1/11 duty, 11 segments to 16 segments).

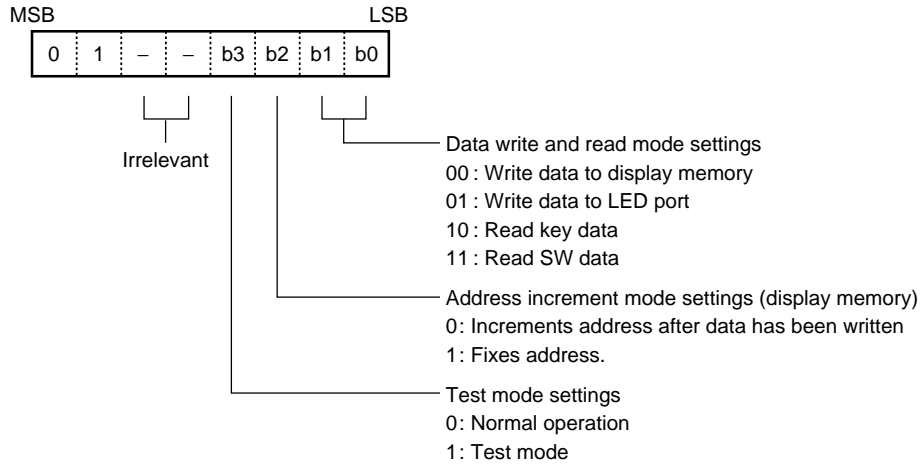
When these commands are executed, the display is forcibly turned off, and key scanning is also stopped. To resume display, the display command “ON” must be executed. If the same mode is selected, however, nothing happens.



On power application, the 11-digit, 11-segment mode is selected.

**(2) Data setting commands**

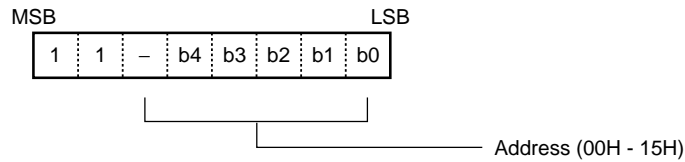
These commands set data write and data read modes.



On power application, the normal operation and address increment modes are set.

**(3) Address setting commands**

These commands set an address of the display memory.

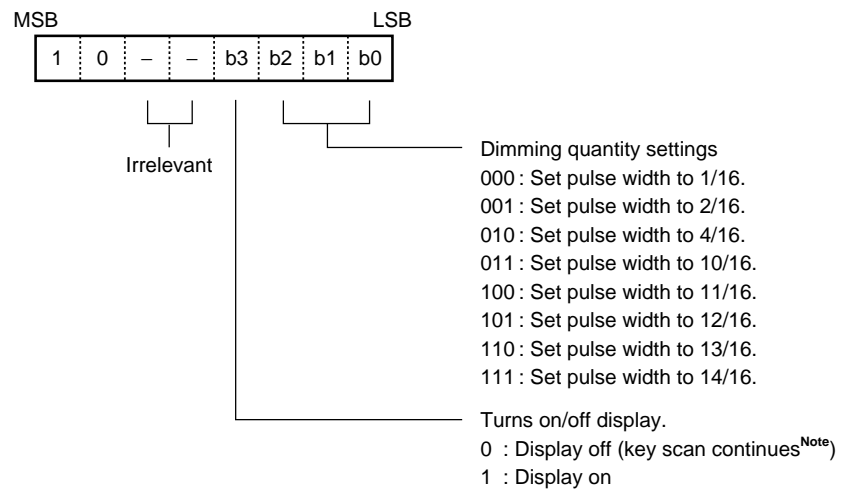


If address 16H or higher is set, data is ignored, until a valid address is set.

On power application, the address is set to 00H.



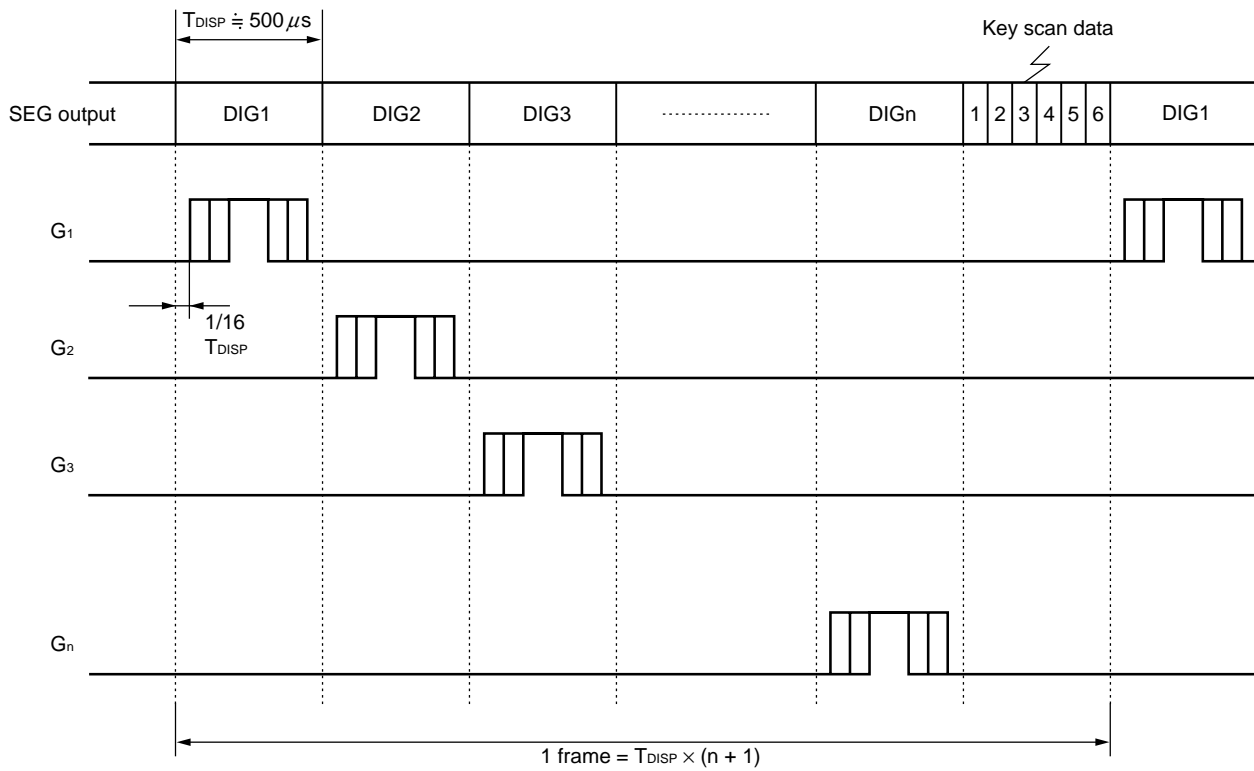
(4) Display control commands



On power application, the 1/16 pulse width is set and the display is turned off.

**Note** On power application, key scanning is stopped.

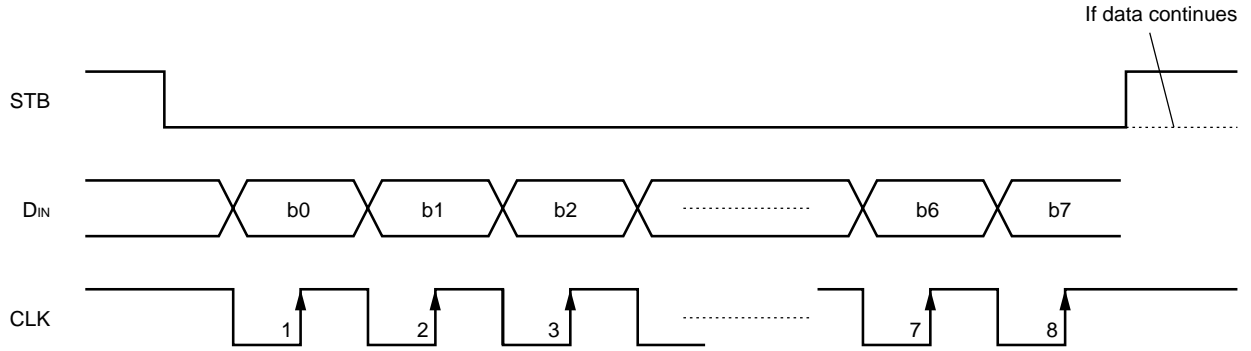
Key Scanning and Display Timing



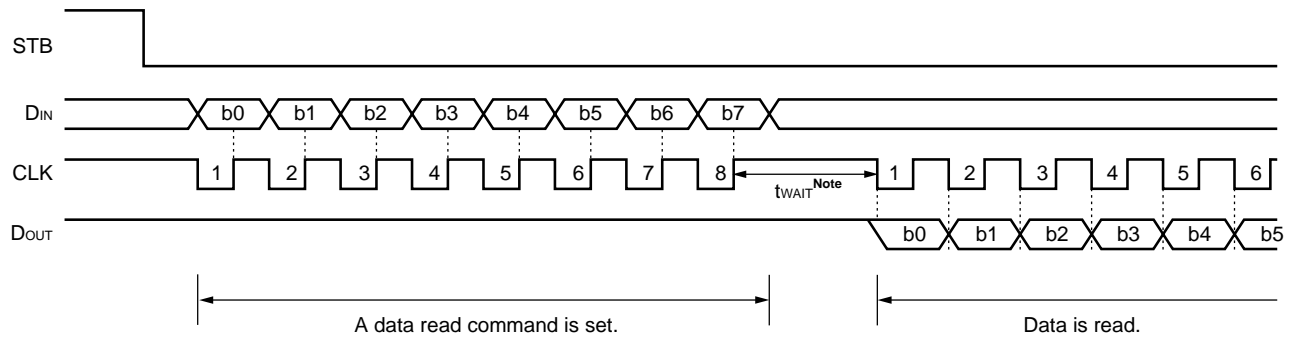
One cycle of key scanning consists of one frame, and data in a 6 × 4 matrix is stored in RAM.

**Serial Communication Format**

Reception (command/data write)



Transmission (data read)



Because the D<sub>OUT</sub> pin is an N-ch, open-drain output pin, be sure to connect an external pull-up resistor to this pin (1 kΩ to 10 kΩ).

**Note** When data is read, a wait time  $t_{WAIT}$  of 1 μs is necessary since the rising of the eighth clock that has set the command, until the falling of the first clock that has read the data.

**ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub> = 25 °C, V<sub>SS</sub> = 0 V)**

PARAMETER	SYMBOL	RATINGS	UNIT
Logic Supply Voltage	V <sub>DD</sub>	-0.5 to +7.0	V
Driver Supply Voltage	V <sub>EE</sub>	V <sub>DD</sub> +0.5 to V <sub>DD</sub> -40	V
Logic Input Voltage	V <sub>I1</sub>	-0.5 to V <sub>DD</sub> +0.5	V
FIP Driver Output Voltage	V <sub>O2</sub>	V <sub>EE</sub> -0.5 to V <sub>DD</sub> +0.5	V
LED Driver Output Current	I <sub>O1</sub>	+25	mA
FIP Driver Output Current	I <sub>O2</sub>	-40 (grid) -15 (segment)	mA
Power Dissipation	P <sub>D</sub>	800 <sup>Note</sup>	mW
Operating Ambient temperature	T <sub>opt</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-65 to +150	°C

**Note** Derate at -6.4 mW/°C at T<sub>a</sub> = 25 °C or higher.

**RECOMMENDED OPERATING RANGE (T<sub>a</sub> = -20 to 70 °C, V<sub>SS</sub> = 0 V)**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Logic Supply Voltage	V <sub>DD</sub>	4.5	5	5.5	V	
High-Level Input Voltage	V <sub>IH</sub>	0.7 • V <sub>DD</sub>		V <sub>DD</sub>	V	
Low-Level Input Voltage	V <sub>IL</sub>	0		0.3 • V <sub>DD</sub>	V	
Driver Supply Voltage	V <sub>EE</sub>	0		V <sub>DD</sub> - 35	V	

Maximum power consumption P<sub>MAX.</sub> = FIP driver dissipation + R<sub>L</sub> dissipation + LED driver dissipation + dynamic power consumption

Where segment current = 3 mA, grid current = 15 mA, and LED current = 20 mA,

FIP driver dissipation = number of segments × 6 + number of grids/(number of grids + 1) × 30 (mW)

R<sub>L</sub> dissipation = (V<sub>DD</sub> - V<sub>EE</sub>)<sup>2</sup>/50 × (number of segments + 1) (mW)

LED driver dissipation = number of LEDs × 20 (mW)

Dynamic power consumption = V<sub>DD</sub> × 5 (mW)

**Example**

Where V<sub>EE</sub> = -25 V, V<sub>DD</sub> = 5 V, and in 16-segment and 6-digit modes,

FIP driver dissipation = 16 × 6 + 6/7 × 30 = 122

R<sub>L</sub> dissipation = 30<sup>2</sup>/50 × 17 = 306

LED driver dissipation = 4 × 20 = 80

Dynamic power consumption = 5 × 5 = 25

Total 553 mW

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = -20 to +70 °C, V<sub>DD</sub> = 4.5 to 5.5 V, V<sub>SS</sub> = 0 V, V<sub>EE</sub> = V<sub>DD</sub> -35 V)**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
High-Level Output Voltage	V <sub>OH1</sub>	0.9 V <sub>DD</sub>			V	LED <sub>1</sub> - LED <sub>4</sub> , I <sub>OH1</sub> = -1 mA
Low-Level Output Voltage	V <sub>OL1</sub>			1	V	LED <sub>1</sub> - LED <sub>4</sub> , I <sub>OL1</sub> = 20 mA
Low-Level Output Voltage	V <sub>OL2</sub>			0.4	V	D <sub>OUT</sub> , I <sub>OL2</sub> = 4 mA
High-Level Output Current	I <sub>OH21</sub>	-3			mA	V <sub>O</sub> = V <sub>DD</sub> -2 V, Seg <sub>1</sub> to Seg <sub>11</sub>
High-Level Output Current	I <sub>OH22</sub>	-15			mA	V <sub>O</sub> = V <sub>DD</sub> -2 V, Grid <sub>1</sub> to Grid <sub>6</sub> Seg <sub>12</sub> / Grid <sub>11</sub> to Seg <sub>16</sub> / Grid <sub>7</sub>
Driver Leakage Current	I <sub>OLEAK</sub>			-10	μA	V <sub>O</sub> = V <sub>DD</sub> -35 V, driver off
Output Pull-Down Resistor	R <sub>L</sub>	50	100	150	KΩ	Driver output
Input Current	I <sub>I</sub>			±1	μA	V <sub>I</sub> = V <sub>DD</sub> or V <sub>SS</sub>
High-Level Input Voltage	V <sub>IH</sub>	0.7 V <sub>DD</sub>			V	
Low-Level Input Voltage	V <sub>IL</sub>			0.3 V <sub>DD</sub>	V	
Hysteresis Voltage	V <sub>H</sub>		0.35		V	CLK, D <sub>IN</sub> , STB
Dynamic Current Consumption	I <sub>DDdyn</sub>			5	mA	Under no load, display off

**SWITCHING CHARACTERISTICS (T<sub>a</sub> = -20 to +70 °C, V<sub>DD</sub> = 4.5 to 5.5 V, V<sub>EE</sub> = -30 V)**

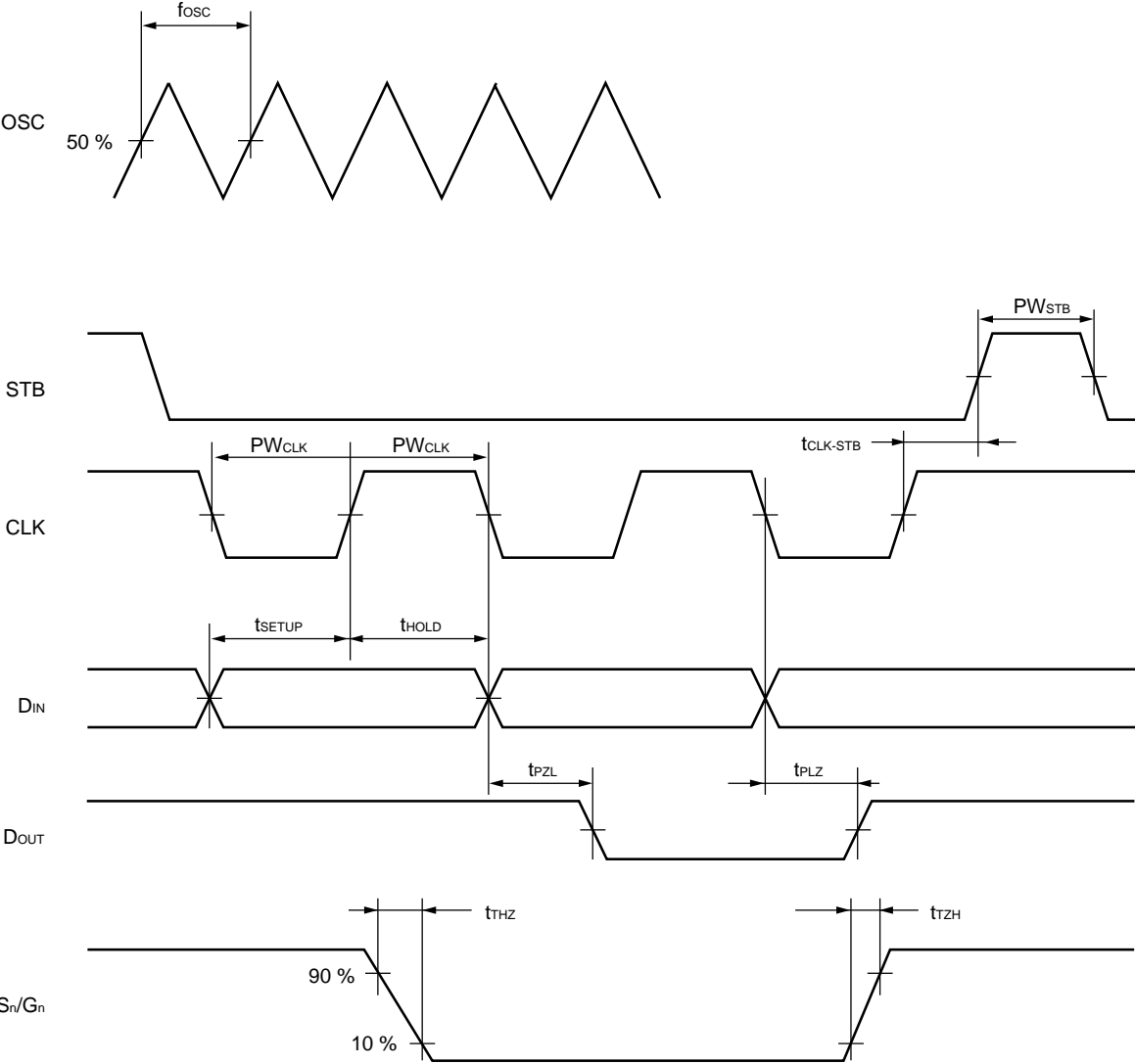
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Oscillation Frequency	t <sub>osc</sub>	350	500	650	kHz	R = 51 kΩ
Propagation Delay Time	t <sub>PLZ</sub>			300	ns	CLK → D <sub>OUT</sub>
	t <sub>PZL</sub>			100	ns	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 10 kΩ
Rise Time	t <sub>TZH1</sub>			2	μs	C <sub>L</sub> = 300 pF Seg <sub>1</sub> to Seg <sub>11</sub> Grid <sub>1</sub> to Grid <sub>6</sub> , Seg <sub>12</sub> /Grid <sub>11</sub> to Seg <sub>16</sub> /Grid <sub>7</sub>
	t <sub>TZH2</sub>			0.5	μs	
Fall Time	t <sub>THZ</sub>			120	μs	C <sub>L</sub> = 300 pF, Seg <sub>n</sub> , Grid <sub>n</sub>
Maximum Clock Frequency	f <sub>max.</sub>	1			MHz	Duty = 50 %
Input Capacitance	C <sub>I</sub>			15	pF	

**TIMING CONDITIONS (T<sub>a</sub> = -20 to 70 °C, V<sub>DD</sub> = 4.5 to 5.5 V)**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Clock Pule Width	PW <sub>CLK</sub>	400			ns	
Strobe Pulse Width	PW <sub>STB</sub>	1			μs	
Data Setup Time	t <sub>SETUP</sub>	100			ns	
Data Hold Time	t <sub>HOLD</sub>	100			ns	
Clock-Strobe Time	t <sub>CLK-STB</sub>	1			μs	CLK ↑ → STB ↑
Wait Time	t <sub>WAIT</sub>	1			μs	CLK ↑ → CLK ↓ <sup>Note</sup>

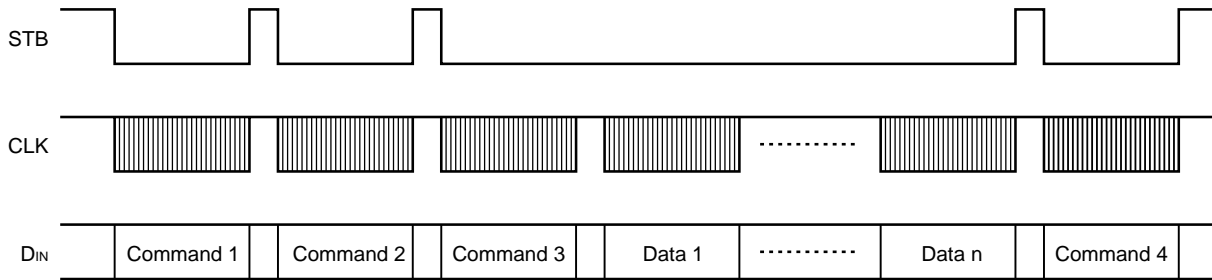
**Note** Refer to page 11.

Switching Characteristic Waveforms



**Applications**

Updating display memory by incrementing address



Command 1: sets display mode

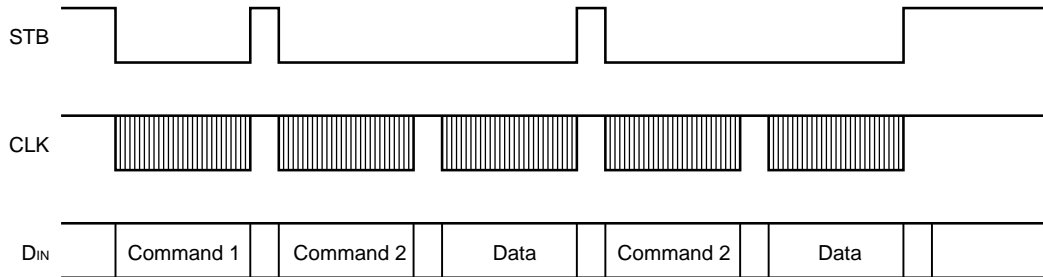
Command 2: sets data

Command 3: sets address

Data 1 to n: transfers display data (22 bytes max.)

Command 4: controls display

Updating specific address



Command 1: sets data

Command 2: sets address

Data: display data

**RECOMMENDED SOLDERING CONDITIONS**

The following conditions (see table below) must be met when soldering this product. Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

**μPC16312GB-3B4**

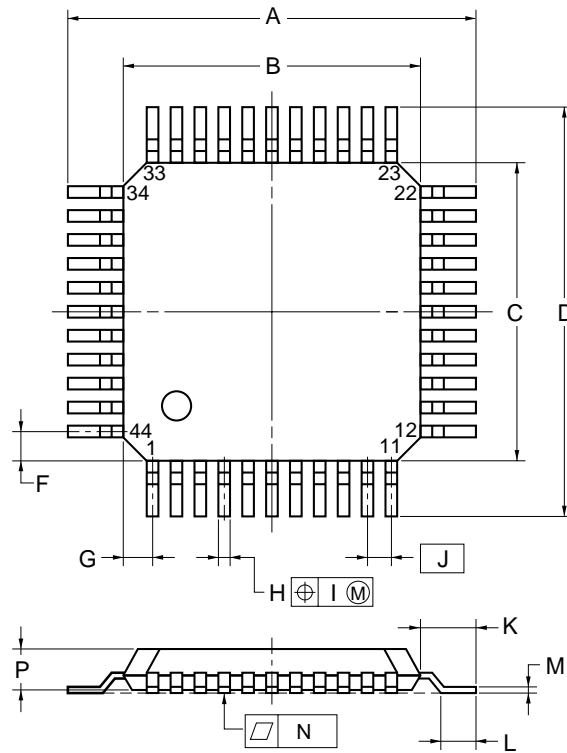
Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package's surface temperature: 235 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 2, Exposure limit*: None	IR35-00-2
VPS	Peak package's surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 2, Exposure limit*: None	VP15-00-2
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below Number of flow process: 1, Exposure limit*: None	WS60-00-1
Partial heating method	Terminal temperature: 300 °C or below, Flow time 10 seconds or below, Exposure limit*: None	

\* Exposure limit before soldering after dry-pack package is opened.  
Storage conditions: 25 °C and relative humidity at 65 % or less.

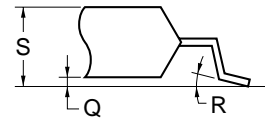
**Note** Do not apply more than a single process at once, except for "Partial heating method".



44 PIN PLASTIC QFP (□10)



detail of lead end



NOTE

Each lead centerline is located within 0.15 mm (0.006 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	13.6±0.4	0.535 <sup>+0.017</sup> <sub>-0.016</sub>
B	10.0±0.2	0.394 <sup>+0.008</sup> <sub>-0.009</sub>
C	10.0±0.2	0.394 <sup>+0.008</sup> <sub>-0.009</sub>
D	13.6±0.4	0.535 <sup>+0.017</sup> <sub>-0.016</sub>
F	1.0	0.039
G	1.0	0.039
H	0.35±0.10	0.014 <sup>+0.004</sup> <sub>-0.005</sub>
I	0.15	0.006
J	0.8 (T.P.)	0.031 (T.P)
K	1.8±0.2	0.071 <sup>+0.008</sup> <sub>-0.009</sub>
L	0.8±0.2	0.031 <sup>+0.009</sup> <sub>-0.008</sub>
M	0.15 <sup>+0.10</sup> <sub>-0.05</sub>	0.006 <sup>+0.004</sup> <sub>-0.003</sub>
N	0.10	0.004
P	2.7	0.106
Q	0.1±0.1	0.004±0.004
R	5°±5°	5°±5°
S	3.0 MAX.	0.119 MAX.

P44GB-80-3B4-3

[MEMO]

[MEMO]

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Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

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Anti-radioactive design is not implemented in this product.